1-of-8 Decoder/Demultiplexer with Address Latch

High-Performance Silicon-Gate CMOS

The MC74HC237 is identical in pinout to the LS137, but has noninverting outputs. The device inputs are compatible with standard CMOS outputs: with pullup resistors, they are compatible with LSTTL outputs.

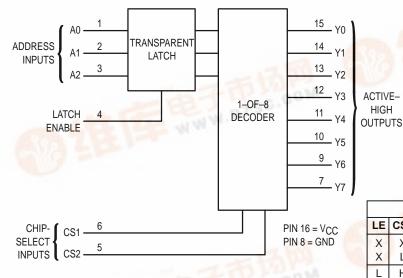
The HC237 decodes a three-bit Address to one-of-eight active-high outputs. The device has a transparent latch for storage of the Address. Two Chip Selects, one active-low and one active-high, are provided to facilitate the demultiplexing, cascading, and chip-selecting functions.

The demultiplexing function is accomplished by using the Address inputs to select the desired device output, and then by using one of the Chip Selects as a data input while holding the other one active.

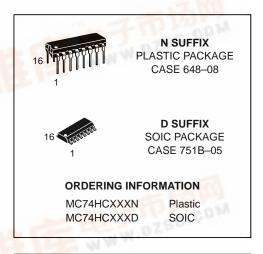
The HC237 is the noninverting version of the HC137.

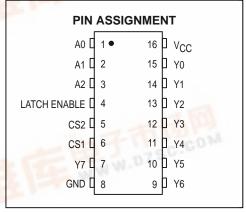
- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 uA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No 7A
- Chip Complexity: 156 FETs or 39 Equivalent Gates

LOGIC DIAGRAM



MC74HC237





FUNCTION TABLE

HIGH

	Inputs							Ou	tput	s			
LE	CS1	CS2	A2	A1	A0	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	Х	Н	Х	Χ	Χ	L	L	L	L	L	L	L	L
X	L	Χ	Χ	Χ	Χ	L	L	L	L	L	L	L	L
L	Н	L	L	L	Г	Н	L	L	L	L	L	L	L
L	Н	L	L	L	Н	L	Н	L	L	L	L	L	L
L	Н	L	L	Н	L	L	L	Н	L	L	L	L	L
L	Н	L	L	Н	Н	L	L	L	Н	L	L	L	L
L	Н	L	Н	L	Г	L	L	L	L	Н	L	L	L
L	Н	L	Н	L	Н	L	L	L	L	L	Н	L	L
L	Н	L	Н	Н	L	L	L	L	L	L	L	Н	L
L	Н	L	Н	Н	Н	L	L	L	L	L	L	L	Н
Н	Н	L	Χ	Χ	Χ					*			

^{* =} Depends upon the Address previously applied while LE was at a low level.



MC74HC237

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	- 1.5 to V _{CC} + 1.5	V
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
l _{in}	DC Input Current, per Pin	± 20	mA
l _{out}	DC Output Current, per Pin	± 25	mA
Icc	DC Supply Current, V _{CC} and GND Pins	± 50	mA
PD	Power Dissipation in Still Air Plastic DIP† SOIC Package†	750 500	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

SOIC Package: - 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
VCC	DC Supply Voltage (Referenced to GND)			6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)			Vcc	V
TA	Operating Temperature, All Package Types			+ 125	°C
t _r , t _f	Input Rise and Fall Time (Figure 2)	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	V _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
VIH	Minimum High-Level Input Voltage	$V_{Out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{Out} \le 20 \mu\text{A}$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V _{IL}	Maximum Low–Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1 2	V
Voн	Minimum High–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$V_{\text{in}} = V_{\text{IH}} \text{ or } V_{\text{IL}} I_{\text{out}} \le 4.0 \text{ mA}$ $ I_{\text{out}} \le 5.2 \text{ mA}$	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
VOL	Maximum Low–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$V_{\text{in}} = V_{\text{IH}} \text{ or } V_{\text{IL}} I_{\text{out}} \le 4.0 \text{ mA}$ $ I_{\text{out}} \le 5.2 \text{ mA}$	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
l _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	± 0.1	± 1.0	± 1.0	μΑ
lcc	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	6.0	8	80	160	μА

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

^{*} Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

[†]Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_f = t_f = 6 \text{ ns}$)

			Guaranteed Limit			
Symbol	Parameter	v _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
^t PLH	Maximum Propagation Delay, Input A to Output Y (Figures 1 and 6)	2.0 4.5 6.0	235 47 40	295 59 50	355 71 60	ns
^t PHL		2.0 4.5 6.0	185 37 31	230 46 39	280 56 48	
^t PLH	Maximum Propagation Delay, CS2 to Output Y (Figures 2 and 6)	2.0 4.5 6.0	200 40 34	250 50 43	300 60 51	ns
^t PHL		2.0 4.5 6.0	145 29 25	180 36 31	220 44 38	
^t PLH	Maximum Propagation Delay, CS1 to Output Y (Figures 3 and 6)	2.0 4.5 6.0	200 40 34	250 50 43	300 60 51	ns
^t PHL		2.0 4.5 6.0	160 32 27	200 40 34	240 48 41	
^t PLH	Maximum Propagation Delay, Latch Enable to Output Y (Figures 4 and 6)	2.0 4.5 6.0	250 50 43	315 63 54	375 75 64	ns
^t PHL		2.0 4.5 6.0	190 38 32	240 48 41	285 57 48	
tTLH, tTHL	Maximum Output Transition Time, Any Output (Figures 2 and 6)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C _{in}	Maximum Input Capacitance	_	10	10	10	pF

NOTES:

- 1. For propagation delays with loads other than 50 pF, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).
- 2. Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

Ī			Typical @ 25°C, V _{CC} = 5.0 V	
	C_{PD}	Power Dissipation Capacitance (Per Package)*	100	pF

^{*} Used to determine the no–load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

TIMING REQUIREMENTS (Input $t_f = t_f = 6 \text{ ns}$)

			Guaranteed Limit			
Symbol	Parameter	V _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t _{su}	Minimum Setup Time, Input A to Latch Enable (Figure 5)	2.0 4.5 6.0	100 20 17	125 25 21	150 30 26	ns
th	Minimum Hold Time, Latch Enable to Input A (Figure 5)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
t _W	Minimum Pulse Width, Latch Enable (Figure 4)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t _r , t _f	Maximum Input Rise and Fall Times (Figure 2)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

PIN DESCRIPTIONS

ADDRESS INPUTS

A0, A1, A2 (Pins 1, 2, 3)

Address inputs. These inputs, when the chip is enabled, determine which of the eight outputs is selected.

CONTROL INPUTS

CS1, CS2 (Pins 6, 5)

Chip select inputs. For CS1 at a high level and CS2 at a low level, the chip is enabled and the outputs follow the data inputs (Latch Enable = L). For any other combination of CS1 and CS2, the outputs are at a low level.

Latch Enable (Pin 4)

Latch Enable input. A high level at this input latches the Address. A low level at this input allows the outputs to follow the Address (CS1 = H and CS2 = L).

OUTPUTS

Y0-Y7 (Pins 15, 14, 13, 12, 11, 10, 9, 7)

Active—high outputs. One of these eight outputs is selected when the chip is enabled (CS1 = H and CS2 = L) and the Address inputs correspond to that particular output. The selected output is at a high level while all others remain at a low level.

SWITCHING WAVEFORMS

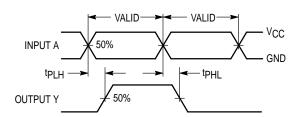


Figure 1.

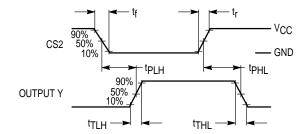


Figure 2.

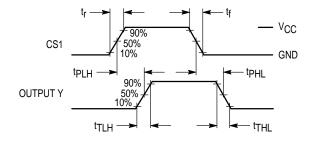


Figure 3.

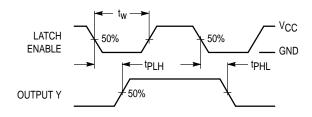


Figure 4.

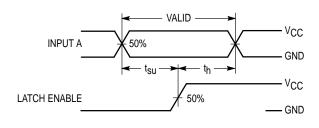
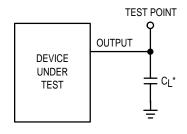


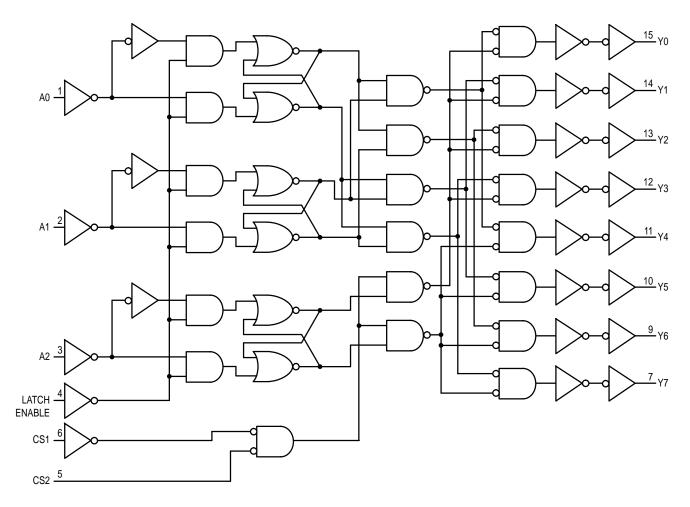
Figure 5.



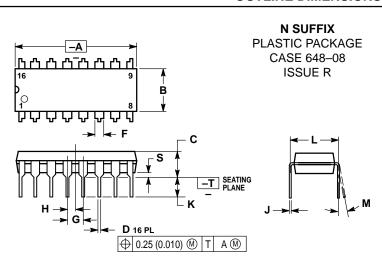
^{*} Includes all probe and jig capacitance

Figure 6. Test Circuit

EXPANDED LOGIC DIAGRAM



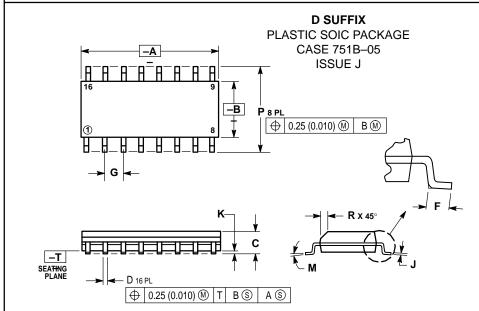
OUTLINE DIMENSIONS



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION L TO CENTER OF LEADS WHEN
 - FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.070	1.02	1.77		
G	0.	100 BSC	2.54 BSC			
Н	0.	.050 BSC	1	.27 BSC		
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
М	0°	10°	0°	10°		
S	0.020	0.040	0.51	1.01		



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14 5M 1982
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006)
 PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIM	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.2	7 BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and "are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

How to reach us:

USA/EUROPE: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036. 1–800–441–2447 JAPAN: Nippon Motorola Ltd.; Tatsumi–SPD–JLDC, Toshikatsu Otsuki, 6F Seibu–Butsuryu–Center, 3–14–2 Tatsumi Koto–Ku, Tokyo 135, Japan. 03–3521–8315

MFAX: RMFAX0@email.sps.mot.com -TOUCHTONE (602) 244-6609 HONG INTERNET: http://Design-NET.com 51 Ting

HONG KONG: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852–26629298

